BRCO7330HME CMOS

300mA 30V CMOS

30V

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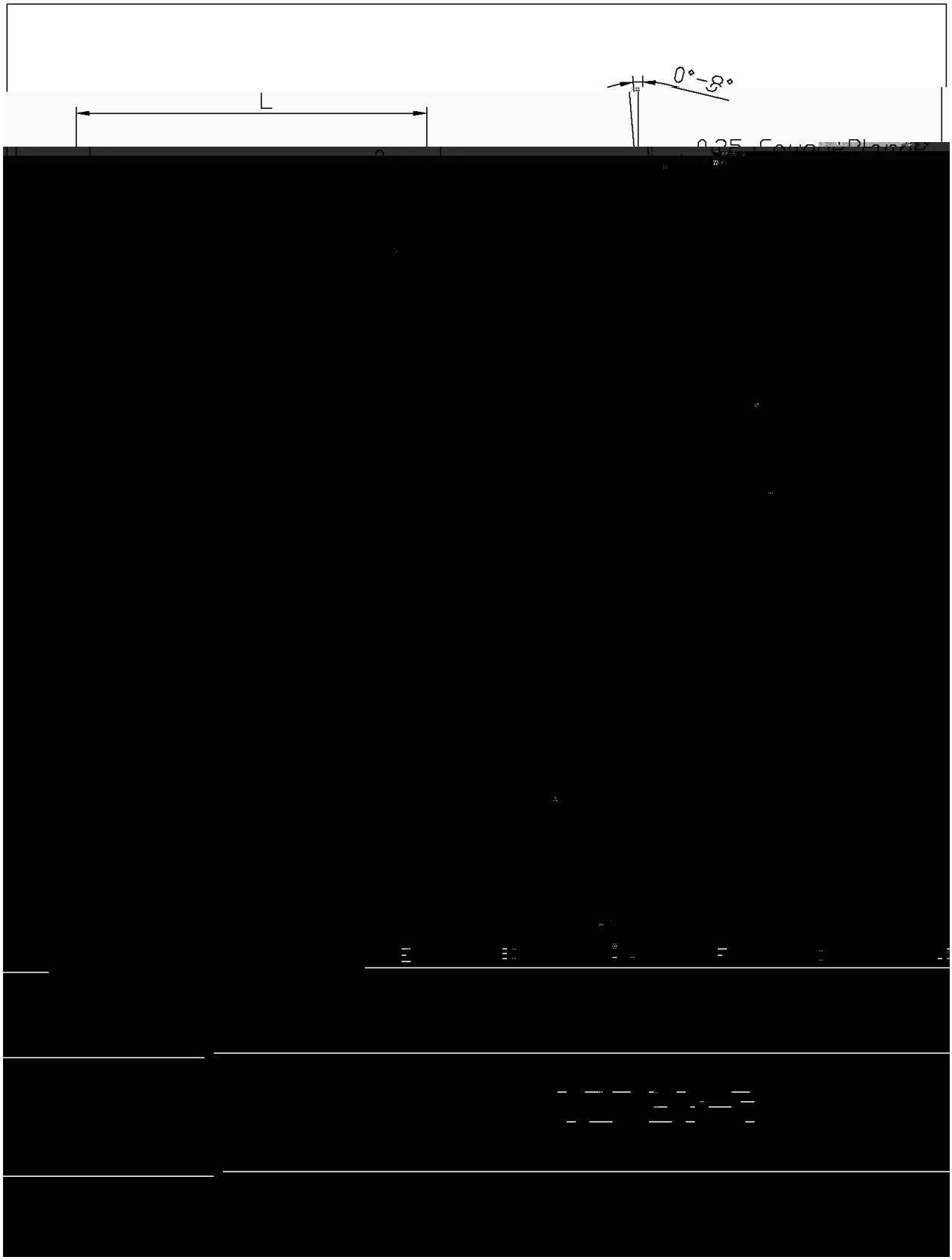
	V_{IN_MAX}	30	V
	V_{IN}	-0.3~30	V
CE	V_{CE}	V_{IN}-0.3~V_{IN}+0.3	V
	I_{OUT}	0~500	mA
	P_D	0.3	W
	T_{stg}	-40 to +150	°C
	T_{OP}	-40 to +85	

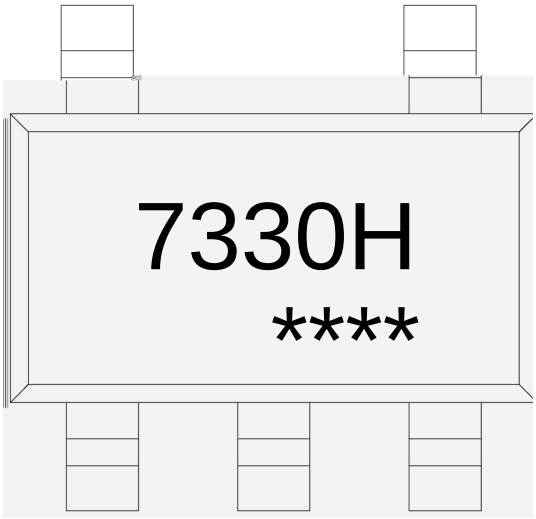
	V_{IN}		2.5		24	V
	V_{OUT}	I_{OUT}=10mA	V_{OUT} *0.98		V_{OUT} *1.02	V
	I_{SS}	I_{OUT}=0mA	-	2.5	6	uA
	I_{ST}	CE=0V			0.2	uA
	L_{LIM}	-	500			mA
	V_{DROP}	I_{OUT}=100mA	-	200	-	mV
	I_{SHORT}			55		mA
	V_{CE_L}				0.4	V
	V_{CE_H}		1.5			V

/ Functionl Block Diagram

/ Package Dimensions



/ Marking Instructions



7330H

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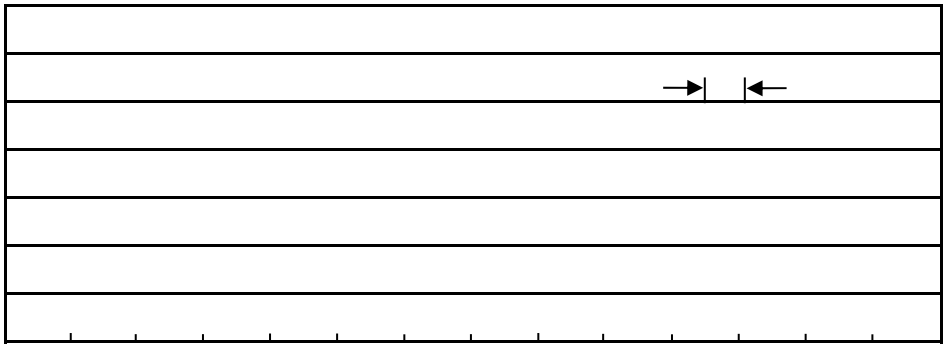
( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



					Note:
1	150	180	60	90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5			5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2	10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOT23-5/6	3,000	10	30,000	4	120,000	7 ×8	210×205×205	445×435×230

/ Notices

All information provided in this document is subject to legal disclaimers.